L Number	Hits	Search Text	DB	Time stamp
-	114427		USPAT;	2004/09/01 13:03
		electrodeposit\$4 or electrol\$8 near3	US-PGPUB;	
		deposit\$4 or electrochemical\$2 near3	EPO; JPO;	
		deposit\$ or (electro adj1 chemical\$2)	DERWENT;	
		near3 deposit\$4	IBM_TDB	
-	251638	seed\$4	USPAT;	2004/09/01 13:05
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
_	1837550	fill\$4 or refill\$4	USPAT;	2004/09/01 10:12
	1037330	111141 01 10111141	US-PGPUB;	2001, 03, 01 10112
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	1159899	copper or cu	USPAT;	2004/09/01 09:02
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	697397	photorogist or regist or photosepsitive or	IBM_TDB USPAT;	2004/09/01 12:58
}	051391	photoresist or resist or photosensitive or   photo adj2 sensitive	US-PGPUB;	2004,00,01 12.00
		1	EPO; JPO;	
			DERWENT;	
[			IBM_TDB	
1-	1173993	, =	USPĀT;	2004/09/01 09:04
]		connect\$4	US-PGPUB;	
1			EPO; JPO;	
			DERWENT;	
	202740	handan C 4	IBM_TDB USPAT;	2004/09/01 09:42
-	392748	harden\$4	US-PGPUB;	2004/09/01 09:42
			EPO; JPO;	5
			DERWENT;	
			IBM TDB	
-	5058080	groove or trench or hole or aperture or	USPAT;	2004/09/01 13:04
		opening	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	7710	(	IBM_TDB USPAT;	2004/09/01 10:14
_	7713	(copper or cu) with (fill\$4 or refill\$4) with (groove or trench or hole or aperture	US-PGPUB;	2004/09/01 10:14
		or opening)	EPO; JPO;	
		or oponing,	DERWENT;	
			IBM TDB	
-	13795	seed\$4 with (groove or trench or hole or	USPĀT;	2004/09/01 10:14
		aperture or opening)	US-PGPUB;	
]			EPO; JPO;	
1			DERWENT;	
1_	597	(electroplat\$4 or electro adj2 plat\$4 or	IBM_TDB USPAT;	2004/09/01 10:17
	391	electrodeposit\$4 or electrol\$8 near3	US-PGPUB;	2003,05,01 10.17
1		deposit\$4 or electrochemical\$2 near3	EPO; JPO;	
		deposit\$ or (electro adj1 chemical\$2)	DERWENT;	
1		near3 deposit\$4) same ((copper or cu) with	IBM_TDB	
		(fill\$4 or refill\$4) with (groove or		
]		trench or hole or aperture or opening))		
1		same (seed\$4 with (groove or trench or		
1_	276	hole or aperture or opening)) ((electroplat\$4 or electro adj2 plat\$4 or	USPAT;	2004/09/01 14:28
	2/0	electropiats4 or electro adjz plats4 or   electrodeposits4 or electrols8 near3	US-PGPUB;	2003,03,01 14.20
1		deposit\$4 or electrochemical\$2 near3	EPO; JPO;	
		deposit\$ or (electro adj1 chemical\$2)	DERWENT;	
		near3 deposit\$4) same ((copper or cu) with	IBM_TDB	
		(fill\$4 or refill\$4) with (groove or	_	
		trench or hole or aperture or opening))		
		same (seed\$4 with (groove or trench or		
		hole or aperture or opening))) and (photoresist or resist or photosensitive		
		or photo adj2 sensitive)		
L	L	LAT PHOTO GATE SCHOTCIAE	<u> </u>	

- 114427 electroplat\$4 or electro adj2 plat\$4 or USPAT;	2004/09/01 12:58
electrodeposit\$4 or electrol\$8 near3 US-PGPUB;	
deposit\$4 or electrochemical\$2 near3   EPO; JPO;	
deposit\$ or (electro adj1 chemical\$2)   DERWENT;	
near3 deposit\$4 IBM_TDB	
- 995720 photoresist or resist or photosensitive or USPAT;	2004/09/01 12:59
photo adj2 sensitive or polymeric US-PGPUB;	
EPO; JPO;	
DERWENT;	
IBM_TDB	
- 2422381 (photoresist or resist or photosensitive USPAT;	2004/09/01 13:00
or photo adj2 sensitive or polymeric ) or US-PGPUB;	
polymer or polyimide EPO; JPO;	•
DERWENT;	
IBM_TDB	
- 1175302 hard or hardern\$4 or cure\$1 or curing USPAT;	2004/09/01 13:02
US-PGPUB;	1
EPO; JPO;	
DERWENT;	
IBM_TDB	0004/00/01 13 03
- 107409 ((photoresist or resist or photosensitive USPAT;	2004/09/01 13:03
or photo adj2 sensitive or polymeric ) or US-PGPUB;	
polymer or polyimide) with (hard or EPO; JPO;	
hardern\$4 or cure\$1 or curing)  DERWENT;	1
IBM_TDB	2004/09/01 13:04
- 114427 electroplat\$4 or electro adj2 plat\$4 or USPAT;	
electrodeposit\$4 or electrol\$8 near3 US-PGPUB; deposit\$4 or electrochemical\$2 near3 EPO; JPO;	
deposit\$4 or electrochemical\$2 near3	
near3 deposit\$4 lbm TDB	
- 5058080 groove or trench or hole or aperture or USPAT;	2004/09/01 13:04
opening US-PGPUB;	
EPO; JPO;	
DERWENT;	Į.
IBM TDB	
- 251638 seed\$4 USPAT;	2004/09/01 13:05
US-PGPUB;	
EPO; JPO;	
DERWENT;	
IBM TDB	
- 2413 (electroplat\$4 or electro adj2 plat\$4 or USPAT;	2004/09/01 13:07
electrodeposit\$4 or electrol\$8 near3 US-PGPUB;	
deposit\$4 or electrochemical\$2 near3   EPO; JPO;	
deposit\$ or (electro adj1 chemical\$2) DERWENT;	
near3 deposit\$4 ) same (groove or trench IBM_TDB	
or hole or aperture or opening ) same	
seed\$4	0004/00/04 44 45
- 12579 (metal\$4 or conduct\$4 or wire or wiring or USPAT;	2004/09/01 14:12
stud) with (pattern\$3) with (remov\$3) with US-PGPUB;	
((photoresist or resist or photosensitive EPO; JPO;	
or photo adj2 sensitive or polymeric ) or DERWENT;	
polymer or polyimide) IBM_TDB   164   ((electroplat\$4 or electro adj2 plat\$4 or USPAT;	2004/09/01 13:13
	,
electrodeposit\$4 or electrol\$8 near3 US-PGPUB; deposit\$4 or electrochemical\$2 near3 EPO; JPO;	
deposits or (electro adj1 chemical\$2) DERWENT;	
near3 deposit\$4 ) same (groove or trench IBM TDB	
or hole or aperture or opening ) same	
seed\$4 ) and ((metal\$4 or conduct\$4 or	
wire or wiring or stud) with (pattern\$3)	
with (remov\$3) with ((photoresist or	
resist or photosensitive or photo adj2	
sensitive or polymeric ) or polymer or	

= -	82		USPAT;	2004/09/01 13:40
		electrodeposit\$4 or electrol\$8 near3	US-PGPUB;	
		deposit\$4 or electrochemical\$2 near3	EPO; JPO;	
		deposit\$ or (electro adj1 chemical\$2)	DERWENT;	
	ļ	near3 deposit\$4 ) same (groove or trench	IBM_TDB	
		or hole or aperture or opening ) same		
		seed\$4 ) and ((metal\$4 or conduct\$4 or		
	1	wire or wiring or stud) with (pattern\$3)		
	ļ	with (remov\$3) with ((photoresist or		
		resist or photosensitive or photo adj2		
1	ĺ	sensitive or polymeric ) or polymer or		
		polyimide))) and (hard or hardern\$4 or		
_	4707	cure\$1 or curing)   438/618.ccls. or 438/622.ccls. or	HCDAT.	2004/09/01 13:40
-	4/0/	438/623.ccls. or 438/622.ccls. or 438/623.ccls.	USPAT; US-PGPUB;	2004/09/01 13:40
		430/023.0013. 01 430/03/.0013.	EPO; JPO;	
1	1		DERWENT;	
			IBM TDB	
_	453	(438/618.ccls. or 438/622.ccls. or	USPĀT;	2004/09/01 13:40
		438/623.ccls. or 438/637.ccls.) and	US-PGPUB;	
		(electroplat\$4 or electro adj2 plat\$4 or	EPO; JPO;	
		electrodeposit\$4 or electrol\$8 near3	DERWENT;	
		deposit\$4 or electrochemical\$2 near3	IBM TDB	
		deposit\$ or (electro adj1 chemical\$2)	_	
		near3 deposit\$4 ) and seed\$4		
_	1492	(metal\$4 or conduct\$4 or wire or wiring or	USPAT;	2004/09/01 14:13
		stud) with (pattern\$3) with (liftoff or	US-PGPUB;	
		lift\$3 adj2 off) with ((photoresist or	EPO; JPO;	
		resist or photosensitive or photo adj2	DERWENT;	
		sensitive or polymeric ) or polymer or	IBM_TDB	
		polyimide)		
-	10	, ,	USPAT;	2004/09/01 14:14
		electrodeposit\$4 or electrol\$8 near3	US-PGPUB;	
		deposit\$4 or electrochemical\$2 near3	EPO; JPO;	
		deposit\$ or (electro adj1 chemical\$2)	DERWENT;	
		near3 deposit\$4 ) same (groove or trench	IBM_TDB	
		or hole or aperture or opening ) same		
		seed\$4 ) and ((metal\$4 or conduct\$4 or		
		wire or wiring or stud) with (pattern\$3) with (liftoff or lift\$3 adj2 off) with		
		((photoresist or resist or photosensitive		
		or photo adj2 sensitive or polymeric ) or		
		polymer or polyimide))		
	L	porymer or poryimide//		L